
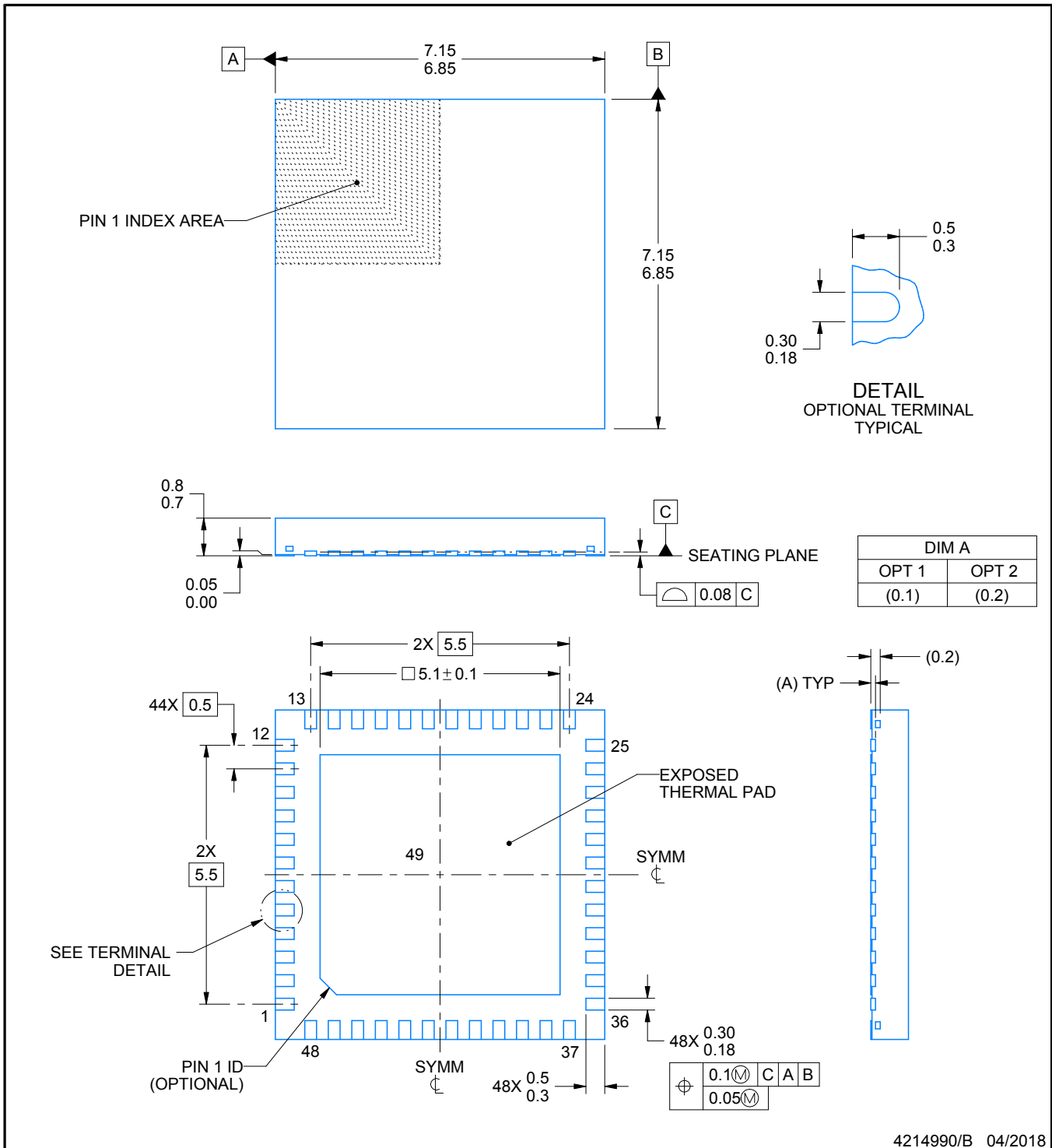
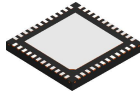


DATA BOOK PACKAGE OUTLINE

LEADFRAME EXAMPLE

4218650

DRAFTER: T. LEQUANG	DATE: 07/06/2016		DIMENSIONS IN MILLIMETERS
DESIGNER:	DATE:	 TEXAS INSTRUMENTS <small>SEMICONDUCTOR OPERATIONS</small>	<small>CODE IDENTITY NUMBER</small> 01295
CHECKER: K. SINCERBOX	DATE: 04/30/2018		
ENGINEER: R. JAVIER	DATE: 04/30/2018		
APPROVED: D. CHIN & D. BABARAN	DATE: 04/30/2018		
RELEASED: WDM	DATE: 04/30/2018		
TEMPLATE INFO: EDGE# 4218519	DATE: 04/07/2016	ePOD, RHS0048A / WQFN, 48 PIN, 0.5 MM PITCH	
		<small>SCALE</small> NTS	<small>SIZE</small> A
		4214990	<small>REV</small> B
			<small>PAGE</small> 1 OF 5



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NOTES:

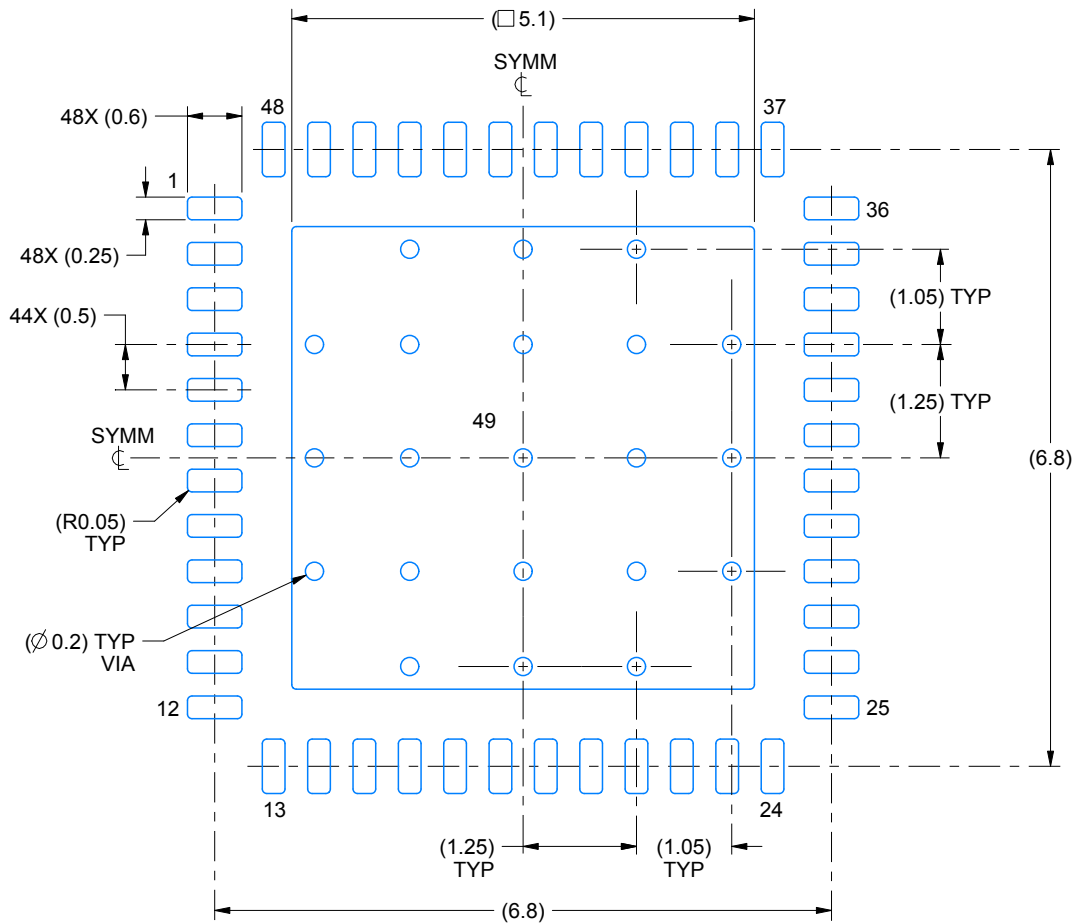
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

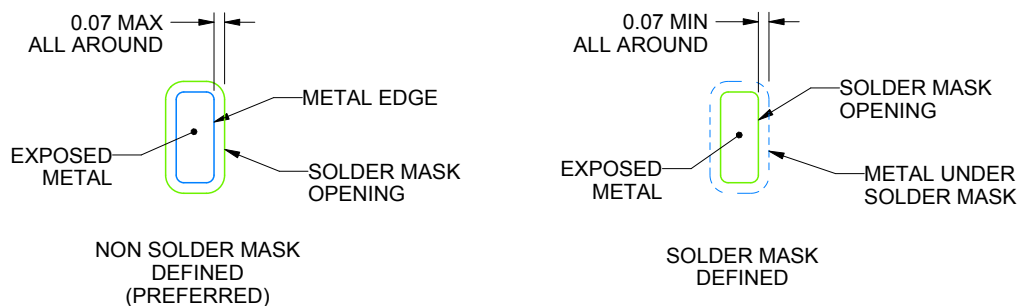
RHS0048A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:12X



SOLDER MASK DETAILS

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NOTES: (continued)

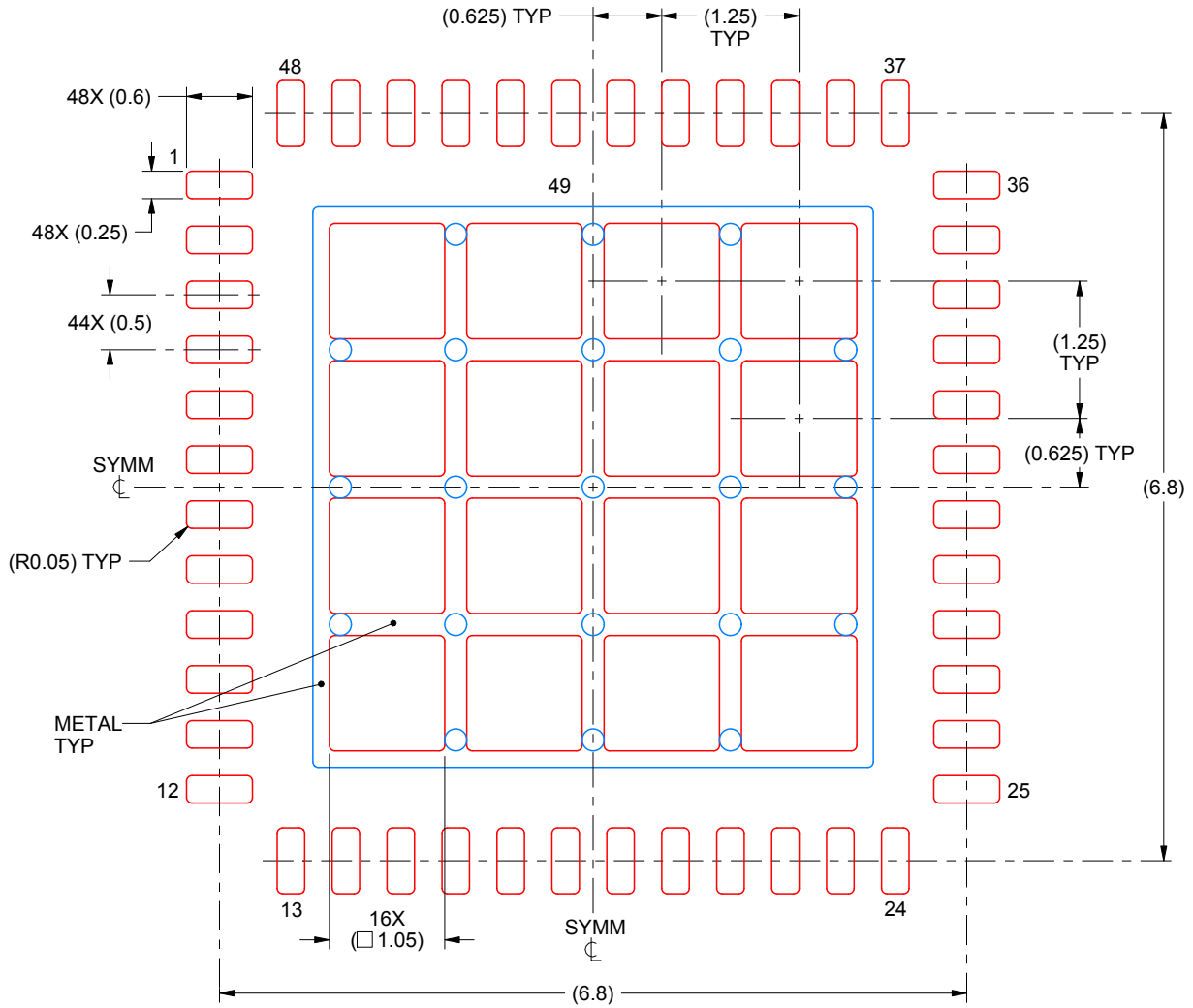
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RHS0048A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 49
68% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:15X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	2158368	07/06/2016	S.V. HUANG / T. LEQUANG
B	ADJUST PACKAGE TOLERANCES TO SUPPORT BOTH THE OLD NSC PACKAGE AND CURRENT TI PACKAGE, SHARED DESIGNATOR; CHANGE SOLDER PASTE TO A 4X4 ARRAY;	2173512	04/30/2018	R. JAVIER / K. SINCERBOX